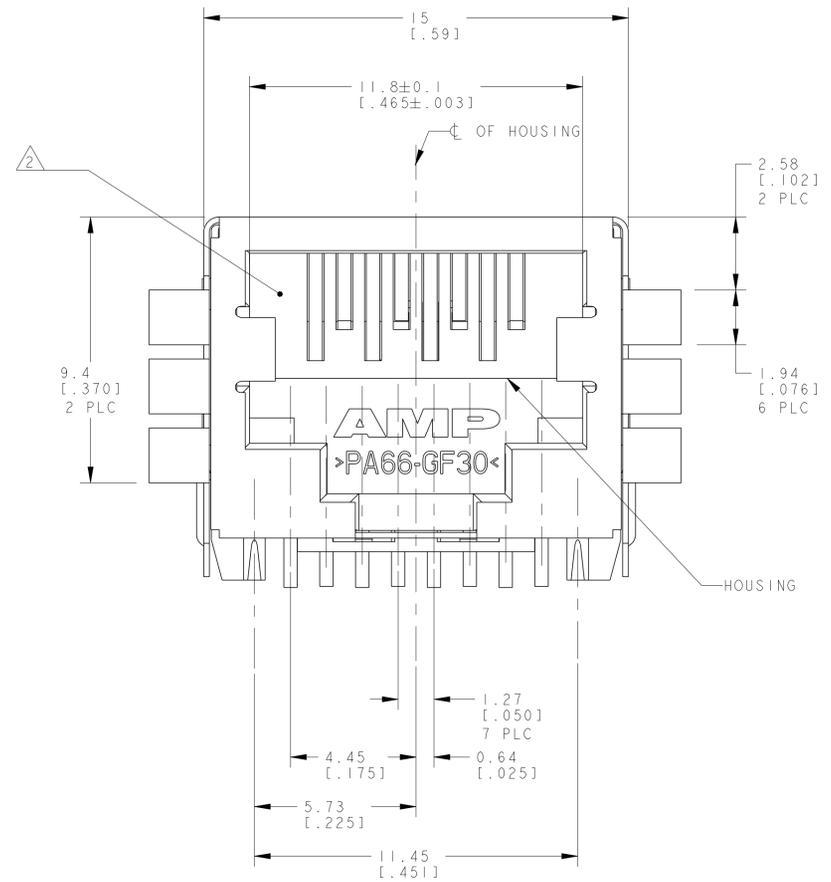
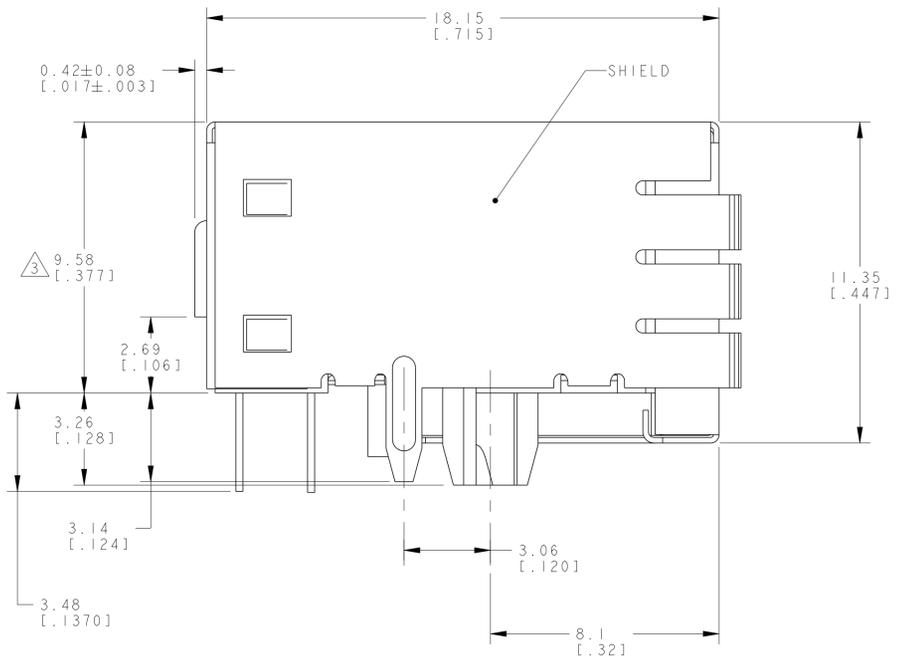
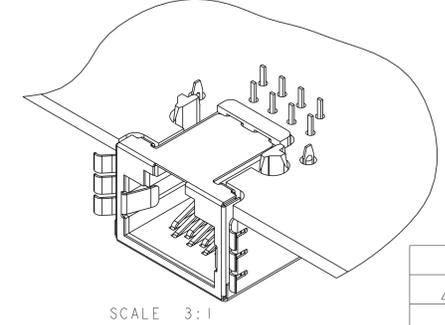
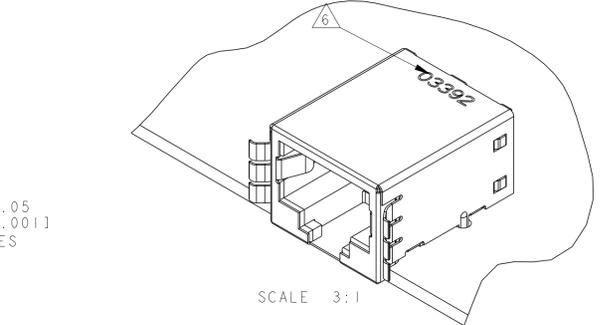
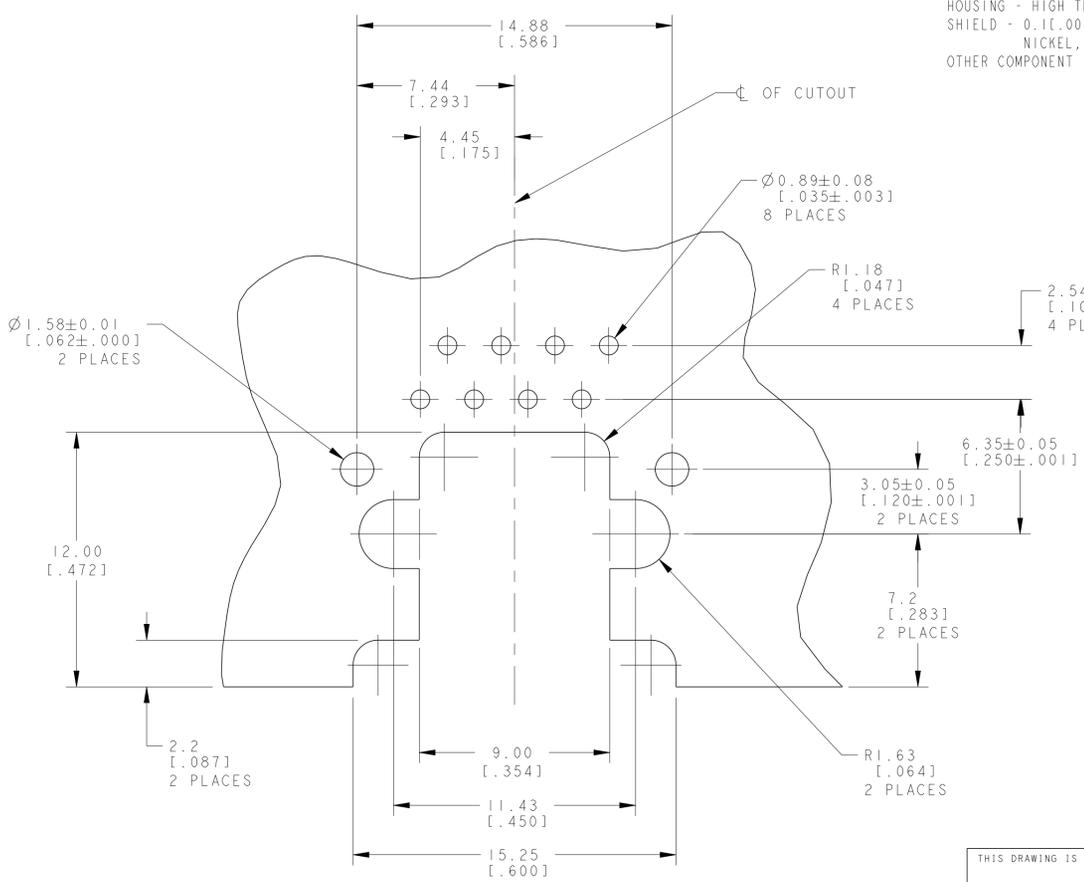
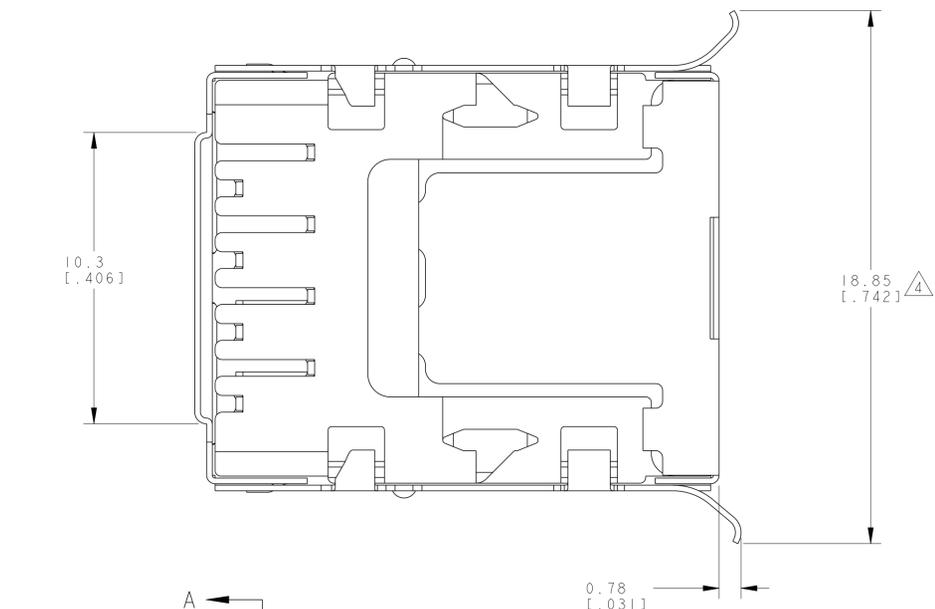


LOC		DIST		REVISIONS			
AA	22	P	LTN	DESCRIPTION	DATE	OWN	APVD
		T		ECO-14-015233	24APR2015	LL	SH
		U		CREATE NEW PN -5	17JUL2017	LL	SH
		V		REVISED AS PER ECR-23-169440	19APR2023	KV	WH

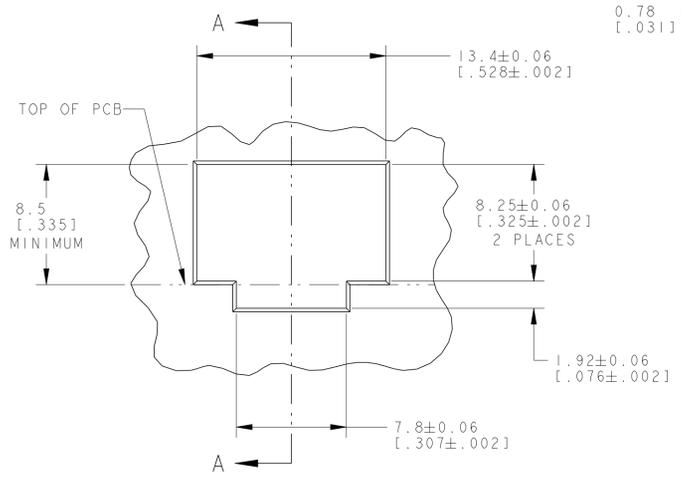


- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25 [ .010 ] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [ .000150 ] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27µm [ .000050 ] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [ .000050 ] MINIMUM THICK NICKEL. SHIELD - 0.1 [ .0039 ] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [ .000079-.000157 ] THICK TIN OVER 1.27µm [ .000050 ] MIN THICK NICKEL.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4 THIS DIMENSION HAS A MAXIMUM VALUE OF 20.50 [ .807 ] WHEN JACK IS INSTALLED BEHIND PANEL.
- 5 PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.
- 6 MANUFACTURING DATE CODE: ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. LASER PRINTING. TEXT HEIGHT APPROXIMATELY 2MM. FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR NEXT 2 DIGITS = MANUFACTURING WORK WEEK LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1
- 7 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25 [ .010 ] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [ .000150 ] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [ .000050 ] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [ .000050 ] MINIMUM THICK NICKEL. SHIELD - 0.1 [ .0039 ] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [ .000050 ] MIN THICK NICKEL AND HOT TIN DIP ON PCB GROUND TABS.
- 8 PACKED WITH TAPE AND REEL PACKAGE.
- 9 MATERIAL: SHIELD - 0.1 [ .0039 ] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [ .000050 ] MIN THICK NICKEL, PCB GROUND TABS DIPPED WITH 2.03µm [ .000080 ] MIN TIN. OTHER COMPONENT: AS SAME AS 7
- 10 PACKED WITH DRY PACKING.
- 11 MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL 94V-0, IR REFLOW SOLDERING PROCESS COMPATIBLE. SHIELD - 0.1 [ .0039 ] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [ .000050 ] MIN THICK NICKEL, PCB GROUND TABS DIPPED WITH 2.03µm [ .000080 ] MIN TIN. OTHER COMPONENT - SAME AS 7



11	1116062-5
10, 9	1116062-4
7, 8	1116062-3
7	1116062-2
1	1116062-1
MATERIAL / FINISH	PART NUMBER

OBsolete



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SCALE 6:1

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		MATERIAL:		FINISH:	
mm [ INCHES ]				SEE P/N TABLE	SEE P/N TABLE		
0 PLC	±	0 PLC	±				
1 PLC	±	1 PLC	±				
2 PLC	±	2 PLC	±				
3 PLC	±	3 PLC	±				
4 PLC	±	4 PLC	±				
ANGLES	±	ANGLES	±				

THIS DRAWING IS A CONTROLLED DOCUMENT.	OWN: J. AHERON 11NOV98	CHK: D. KEMPKA 11NOV98	APVD: D. KEMPKA 11NOV98	NAME: MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm
	PRODUCT SPEC: 108-1163	APPLICATION SPEC: 114-2048	WEIGHT: 3.49 grams	SIZE: CAGE CODE: DRAWING NO: 1100779
				RESTRICTED TO: 1116062
				CUSTOMER DRAWING

STC TE Connectivity

SCALE 8:1 SHEET 1 OF 1 REV V